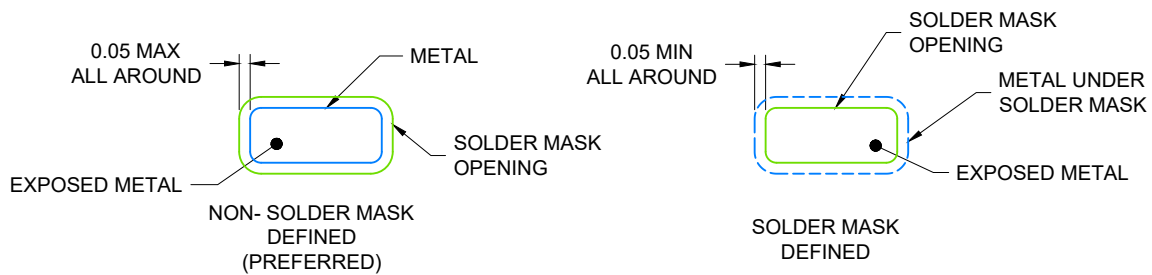


LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 30X

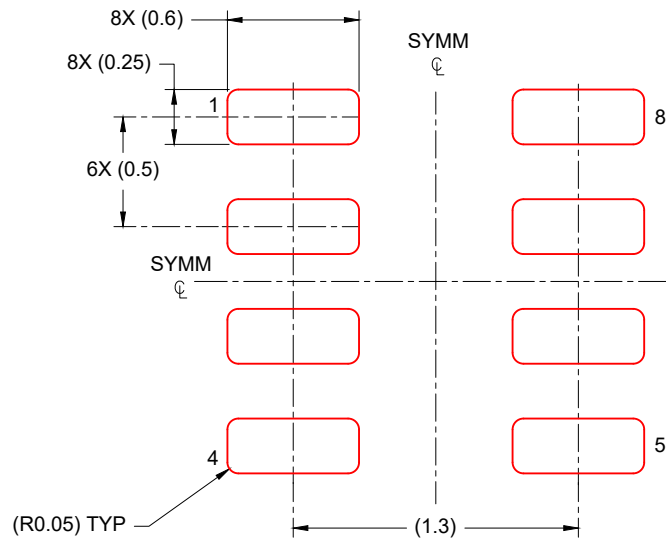


SOLDER MASK DETAILS

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NOTES: (continued)

- For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL  
SCALE: 30X

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NOTES: (continued)

- 4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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